

AN 1993-013832 [02] WPIDS
DNC C1993-006485 [21]
DNN N1993-010402 [21]
TI Mfg. copper@ alloy sheets for electronic components - by forming thin
film of copper@ (alloy) containing tin@, zirconium@, carbon, titanium@ and
silver@ on copper@ alloy sheet
DC L03; M13; P73; U11
IN MANOME M; OZAKI T
PA (HITD-C) HITACHI CABLE LTD
CYC 1
PIA JP 04342159 A 19921127 (199302)* JA 5[3] <--
ADT JP 04342159 A JP 1991-114627 19910520
PRAI JP 1991-114627 19910520
AB JP 04342159 A UPAB: 20050506
Mfr. comprise forming 0.3-3 micron thick thin film of a Cu(-alloy) containing
1 atmospheric% or less in total of Sn, Zr, C, Ti and Ag, on at least one side
of
a sheet of a Cu alloy containing 1-10 atmospheric% in total of Sn, Zr, C, Ti
and Ag.
USE - Exhibits strong adhesion to a different material, and is free
of smut on pickling.